

200-mA Low-Noise, High-PSRR, Negative-Output, Low-Dropout Linear Regulators

Check for Samples: [TPS72301-Q1](#), [TPS72325-Q1](#)

FEATURES

- Qualified for Automotive Applications
- Ultralow Noise: 60 μV_{RMS} Typical
- High PSRR: 65 dB Typical at 1kHz
- Low Dropout Voltage: 280 mV Typical at 200 mA, 2.5 V
- Available in -2.5 V and Adjustable (-1.2 V to -10 V) Versions
- Stable With a 2.2- μF Ceramic Output Capacitor
- Less Than 2- μA Typical Quiescent Current in Shutdown Mode
- 2% Overall Accuracy (Line, Load, Temperature)
- Thermal and Overcurrent Protection
- SOT23-5 (DBV) Package
- Operating Junction Temperature Range: -40°C to 125°C

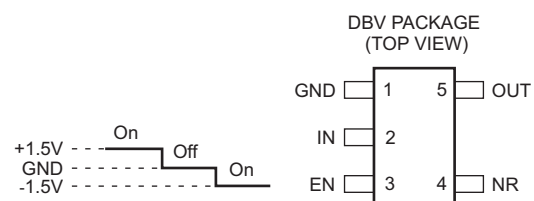
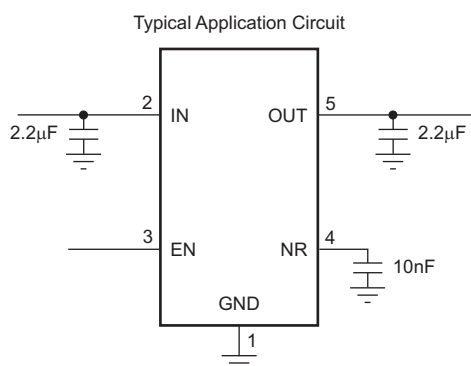
APPLICATIONS

- Optical Drives
- Optical Networking
- Noise-Sensitive Circuitry
- GaAs FET Gate Bias
- Video Amplifiers

DESCRIPTION

The TPS723xx-Q1 family of low-dropout (LDO) negative voltage regulators offers an ideal combination of features to support low-noise applications. This device is capable of operating with input voltages from -10 V to -2.7 V . The TPS72325-Q1 regulator is stable with small, low-cost ceramic capacitors, and includes enable (EN) and noise-reduction (NR) functions. Internal detection and shutdown logic provide thermal short-circuit and overcurrent protection. High PSRR (65 dB at 1 kHz) and low noise (60 μV_{RMS}) make the TPS723xx-Q1 ideal for low-noise applications.

The TPS723xx-Q1 uses a precision voltage reference to achieve 2% overall accuracy over load, line, and temperature variations. Available in a small SOT23-5 package, the TPS723xx-Q1 specification covers the full temperature range of -40°C to 125°C .



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION^{(1) (2)}

| PRODUCT | V _{OUT} ⁽²⁾ | TOP-SIDE MARKING |
|-----------------|---------------------------------|------------------|
| TPS72301QDBVRQ1 | Adjustable output voltage | PPHQ |
| TPS72325QDBVRQ1 | Nominal output voltage = 2.5 V | PSBQ |

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.
- (2) Output voltages from –1.2 V to –9 V in 100-mV increments are available. Minimum order quantities apply; contact factory for details and availability.

ABSOLUTE MAXIMUM RATINGS^{(1) (2)}

Over operating temperature range, unless otherwise noted.

| | VALUE | UNITS |
|--|---|-------|
| Input voltage range, V _{IN} | –11 to 0.3 | V |
| Noise reduction pin voltage range, V _{NR} | –11 to 5.5 | V |
| Enable voltage range, V _{EN} | –V _{IN} to 5.5 | V |
| Output current, I _{OUT} | Internally limited | |
| Output short-circuit duration | Indefinite | |
| Continuous total power dissipation, P _D | See Power Dissipation Ratings table | |
| Junction temperature range, T _J | –55 to 150 | °C |
| Storage temperature range, T _{stg} | –65 to 150 | °C |
| Latch-up performance meets 100 mA per AEC-Q100 Class I | 100 | mA |
| ESD ratings | Human-body model | 2000 |
| | Machine model | 200 |
| | Charged-device model | 500 |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to network ground terminal.

POWER DISSIPATION RATINGS

| BOARD | PACKAGE | R _{θJC} | R _{θJA} | DERATING FACTOR ABOVE T _A = 25°C | T _A ≤ 25°C POWER RATING | T _A = 70°C POWER RATING | T _A = 85°C POWER RATING |
|-----------------------|---------|------------------|------------------|---|------------------------------------|------------------------------------|------------------------------------|
| Low-K ⁽¹⁾ | DBV | 64°C / W | 255°C / W | 3.9 mW / °C | 390 mW | 215 mW | 155 mW |
| High-K ⁽²⁾ | DBV | 64°C / W | 180°C / W | 5.6 mW / °C | 560 mW | 310 mW | 225 mW |

- (1) The JEDEC low-K (1s) board design used to derive this data was a 3-inch × 3-inch (7,62-cm × 7,62-cm), two-layer board with 2-ounce (0.071-mm thick) copper traces on top of the board.
- (2) The JEDEC High-K (2s2p) board design used to derive this data was a 3 inch × 3 inch (7,62-cm × 7,62-cm), multilayer board with 1-ounce (0.035-mm thick) internal power and ground planes and 2-ounce (0.071-mm thick) copper traces on the top and bottom of the board.

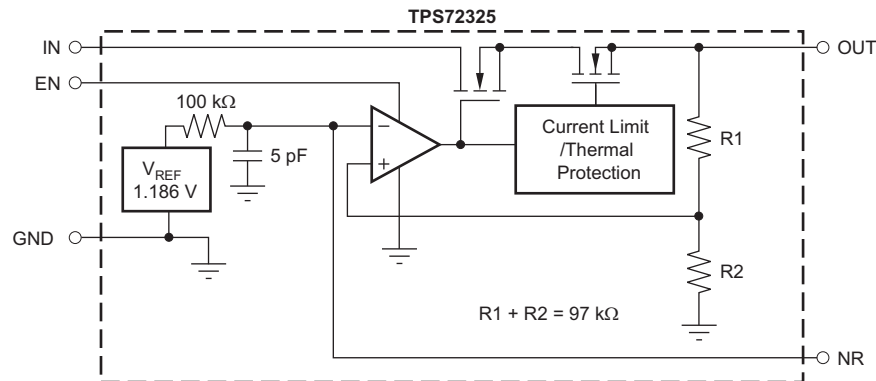
ELECTRICAL CHARACTERISTICS

Over operating junction temperature range, $V_{IN} = V_{OUTnom} - 0.5V$, $I_{OUT} = 1mA$, $V_{EN} = 1.5V$, $C_{OUT} = 2.2\mu F$, and $C_{NR} = 0.01\mu F$, unless otherwise noted. Typical values are at $T_J = 25^\circ C$.

| PARAMETER | | TEST CONDITIONS | TPS723xx-Q1 | | | UNITS |
|-----------------------|---|--|-------------|---------|------|---------------|
| | | | MIN | TYP | MAX | |
| V_{IN} | Input voltage range ⁽¹⁾ | | -10 | | -2.7 | V |
| V_{OUT} | Accuracy | Nominal $T_J = 25^\circ C$ | -1 | | 1 | % |
| | | TPS723xx-Q1 versus $V_{IN} / I_{OUT} / T$ | -2 | ± 1 | 2 | % |
| $V_{OUT}\% / V_{IN}$ | Line regulation | $-10V \leq V_{IN} \leq V_{OUT(nom)} - 0.5V$ | | 0.04 | | % / V |
| $V_{OUT}\% / I_{OUT}$ | Load regulation | $0mA \leq I_{OUT} \leq 200mA$ | | 0.002 | | % / mA |
| V_{DO} | Dropout voltage at $V_{OUT} = 0.96 \times V_{OUTnom}$ | $I_{OUT} = 200mA$ | | 280 | 500 | mV |
| I_{CL} | Current limit | $V_{OUT} = 0.85 \times V_{OUT(nom)}$ | 300 | 550 | 800 | mA |
| I_{GND} | Ground pin current | $I_{OUT} = 0mA (I_Q)$, $-10V \leq V_{IN} \leq V_{OUT} - 0.5V$ | | 130 | 200 | μA |
| | | $I_{OUT} = 200mA$, $-10V \leq V_{IN} \leq V_{OUT} - 0.5V$ | | 350 | 500 | |
| I_{SHDN} | Shutdown ground pin current | $-0.4V \leq V_{EN} \leq 0.4V$, $-10V \leq V_{IN} \leq V_{OUT} - 0.5V$ | | 0.1 | 2 | μA |
| PSRR | Power-supply rejection ratio | $I_{OUT} = 200mA, 1kHz$, $C_{IN} = C_{OUT} = 10\mu F$ | | 65 | | dB |
| | | $I_{OUT} = 200mA, 10kHz$, $C_{IN} = C_{OUT} = 10\mu F$ | | 48 | | |
| V_n | Output noise voltage | $C_{OUT} = 10\mu F, 10Hz$ to $100kHz$, $I_{OUT} = 200mA$ | | 60 | | μV_{RMS} |
| t_{STR} | Startup time | $V_{OUT} = -2.5V, C_{OUT} = 1\mu F$, $R_L = 25\Omega$ | | 1 | | ms |
| $V_{EN(HI)}$ | Enable threshold positive | | 1.5 | | | V |
| $V_{EN(LO)}$ | Enable threshold negative | | | | -1.5 | V |
| $V_{DIS(HI)}$ | Disable threshold positive | | | | 0.4 | V |
| $V_{DIS(LO)}$ | Disable threshold negative | | -0.4 | | | V |
| I_{EN} | Enable pin current | $-10V \leq V_{IN} \leq V_{OUT} - 0.5V$, $-10V \leq V_{EN} \leq \pm 3.5V$ | | 0.1 | 2 | μA |
| T_{SD} | Thermal shutdown temperature | Shutdown, temperature increasing | | 165 | | $^\circ C$ |
| | | Reset, temperature decreasing | | 145 | | |
| T_J | Operating junction temperature | | -40 | | 125 | $^\circ C$ |

(1) Maximum $V_{IN} = (V_{OUT} - V_{DO})$ or $-2.7V$, whichever is more negative.

FUNCTIONAL BLOCK DIAGRAM



TERMINAL FUNCTIONS

| TERMINAL | | DESCRIPTION |
|----------|-----|---|
| NAME | NO. | |
| GND | 1 | Ground |
| IN | 2 | Input supply |
| EN | 3 | Bipolar enable pin. Driving this pin above the positive enable threshold or below the negative enable threshold turns on the regulator. Driving this pin below the positive disable threshold and above the negative disable threshold puts the regulator into shutdown mode. |
| NR | 4 | Fixed-voltage versions only. Connecting an external capacitor between this pin and ground bypasses noise generated by the internal band gap. This configuration allows output noise to be reduced to very low levels. |
| OUT | 5 | Regulated output voltage. The device requires the connection of a small 2.2- μ F ceramic capacitor from this pin to GND to ensure stability. |

TYPICAL CHARACTERISTICS

TPS723xx-Q1 at $V_{IN} = V_{OUTnom} - 0.5\text{ V}$, $I_{OUT} = 1\text{ mA}$, $V_{EN} = 1.5\text{ V}$, $C_{OUT} = 2.2\text{ }\mu\text{F}$, and $C_{NR} = 0.01\text{ }\mu\text{F}$, unless otherwise noted.

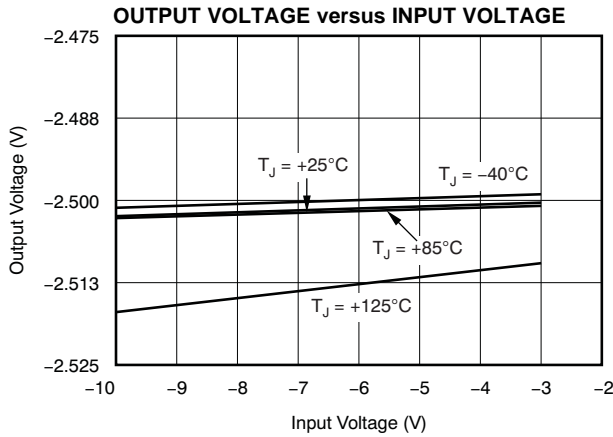


Figure 1.

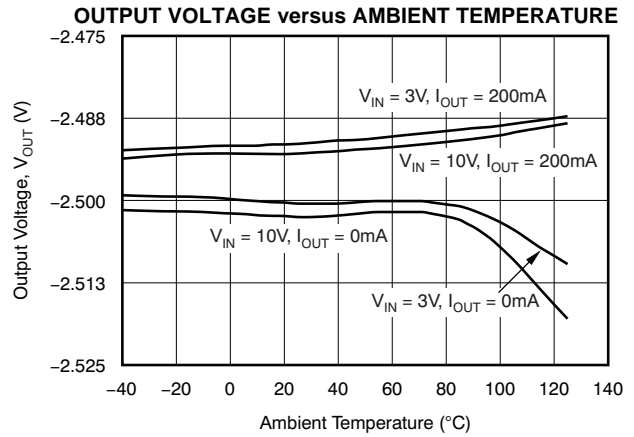


Figure 2.

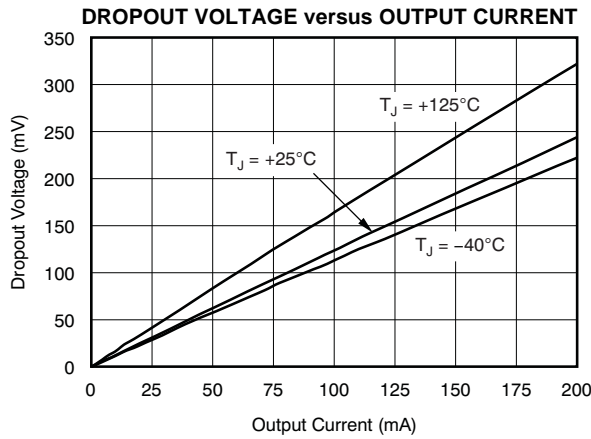


Figure 3.

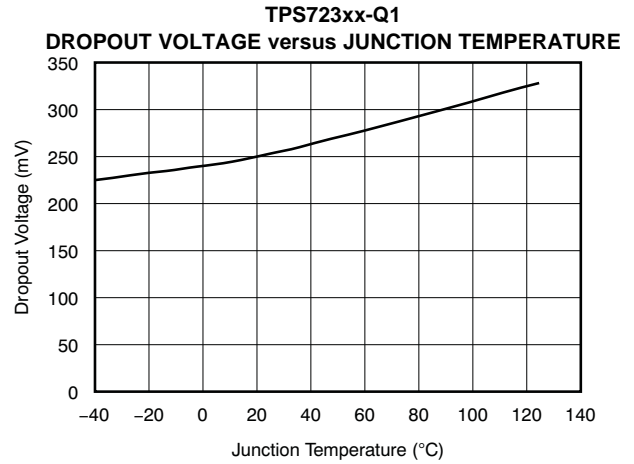


Figure 4.

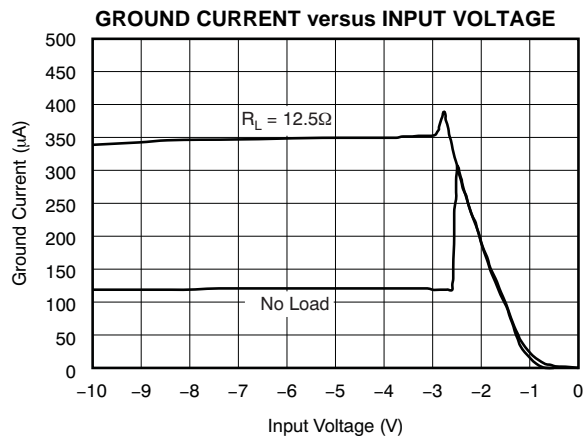


Figure 5.

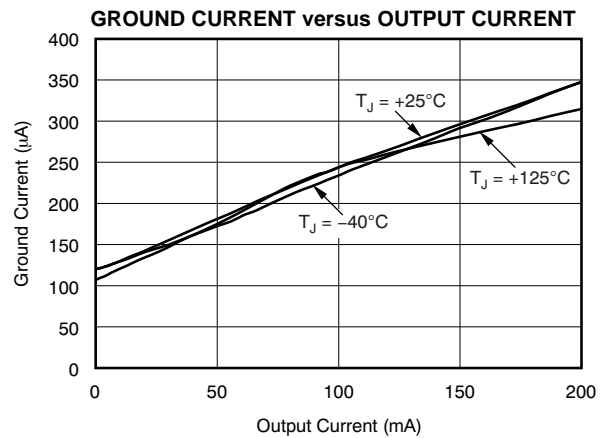


Figure 6.

TYPICAL CHARACTERISTICS (continued)

TPS723xx-Q1 at $V_{IN} = V_{OUTnom} - 0.5\text{ V}$, $I_{OUT} = 1\text{ mA}$, $V_{EN} = 1.5\text{ V}$, $C_{OUT} = 2.2\text{ }\mu\text{F}$, and $C_{NR} = 0.01\text{ }\mu\text{F}$, unless otherwise noted.

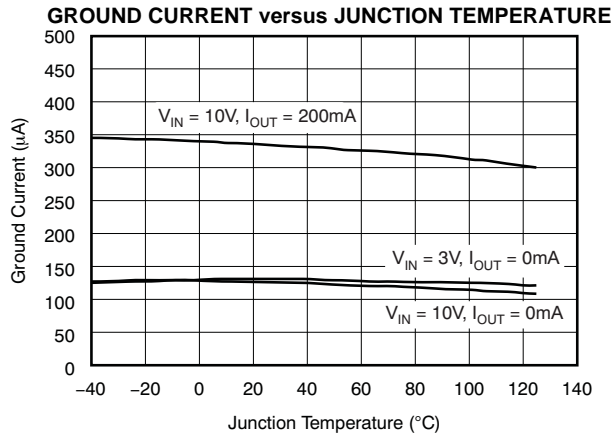


Figure 7.

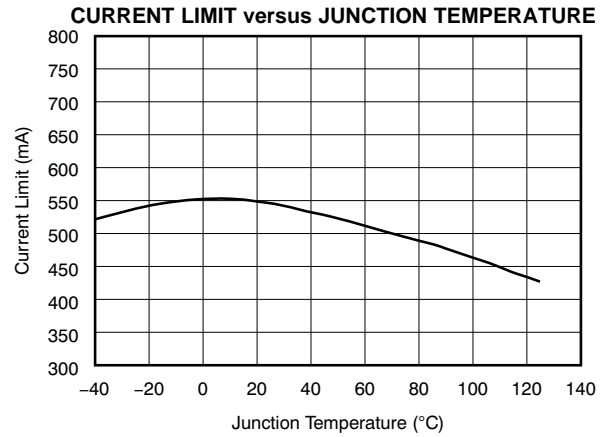


Figure 8.

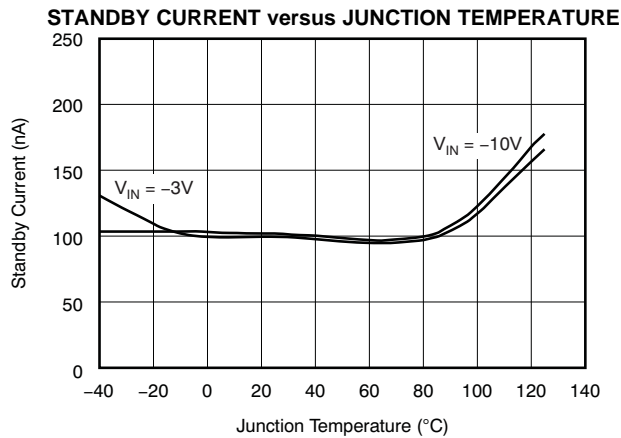


Figure 9.

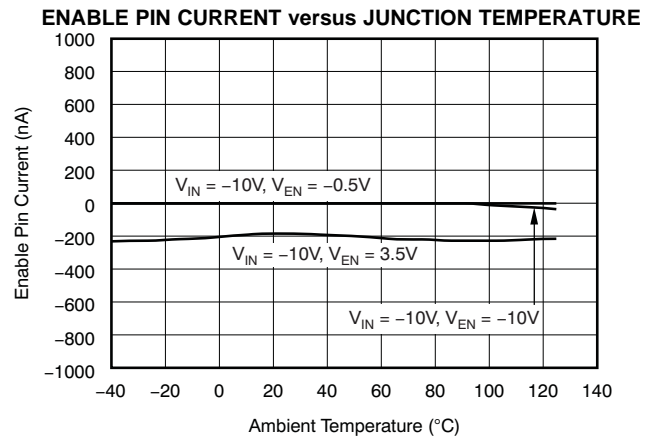


Figure 10.

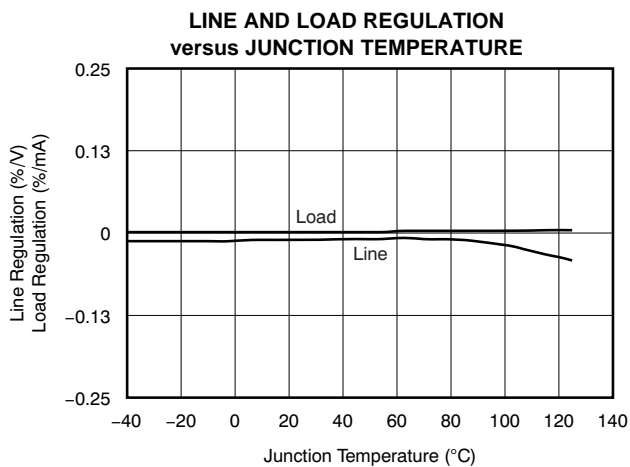


Figure 11.

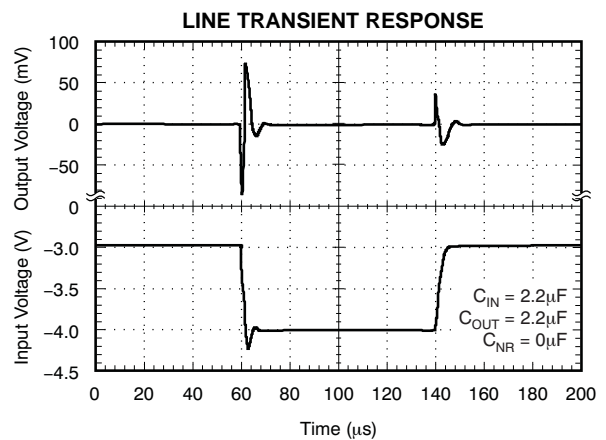


Figure 12.

TYPICAL CHARACTERISTICS (continued)

TPS723xx-Q1 at $V_{IN} = V_{OUTnom} - 0.5\text{ V}$, $I_{OUT} = 1\text{ mA}$, $V_{EN} = 1.5\text{ V}$, $C_{OUT} = 2.2\text{ }\mu\text{F}$, and $C_{NR} = 0.01\text{ }\mu\text{F}$, unless otherwise noted.

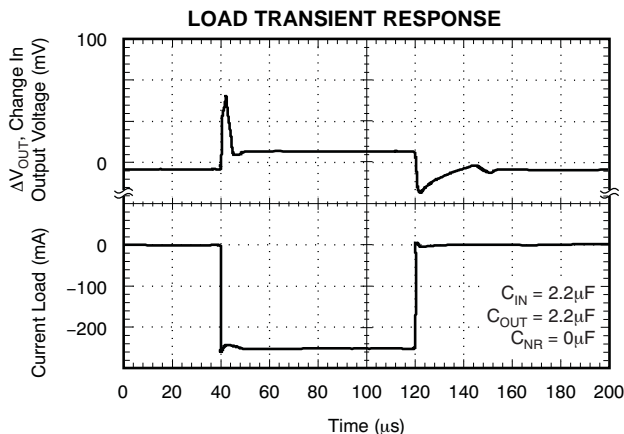


Figure 13.

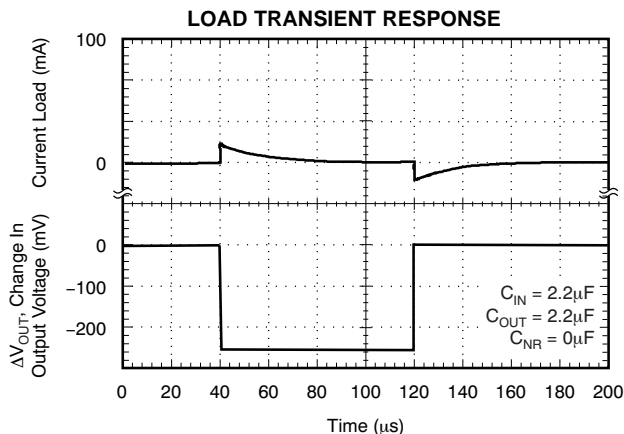


Figure 14.

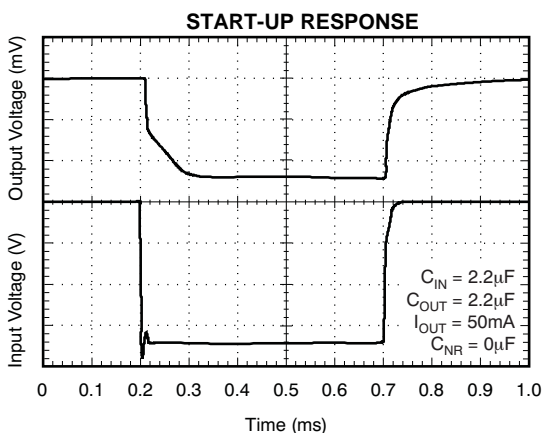


Figure 15.

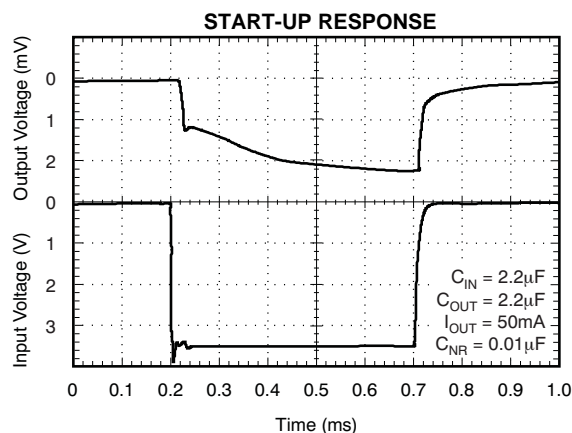


Figure 16.

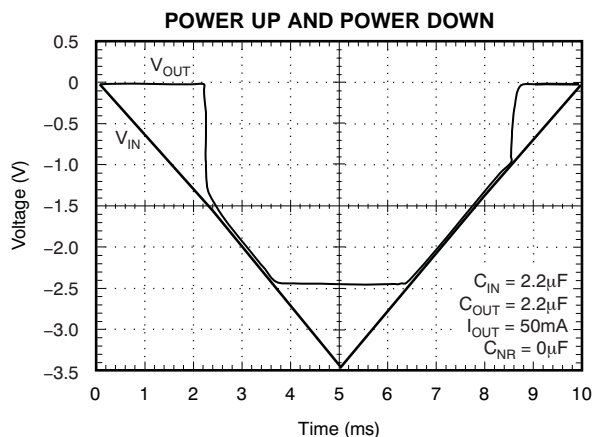


Figure 17.

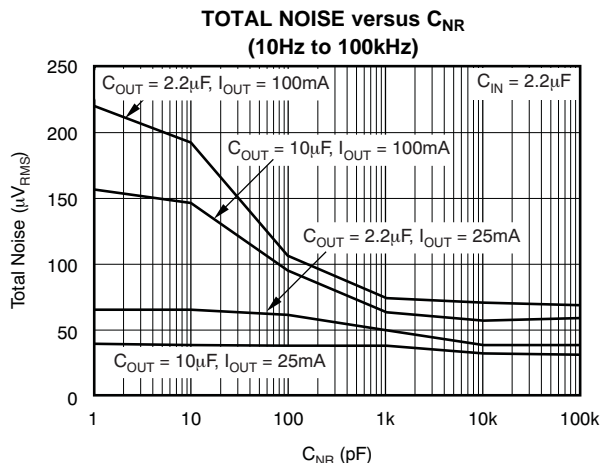


Figure 18.

TYPICAL CHARACTERISTICS (continued)

TPS723xx-Q1 at $V_{IN} = V_{OUTnom} - 0.5\text{ V}$, $I_{OUT} = 1\text{ mA}$, $V_{EN} = 1.5\text{ V}$, $C_{OUT} = 2.2\text{ }\mu\text{F}$, and $C_{NR} = 0.01\text{ }\mu\text{F}$, unless otherwise noted.

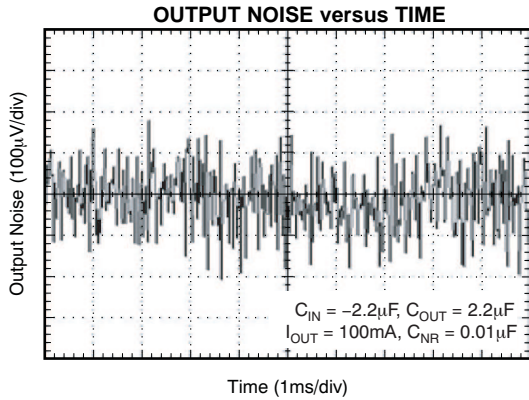


Figure 19.

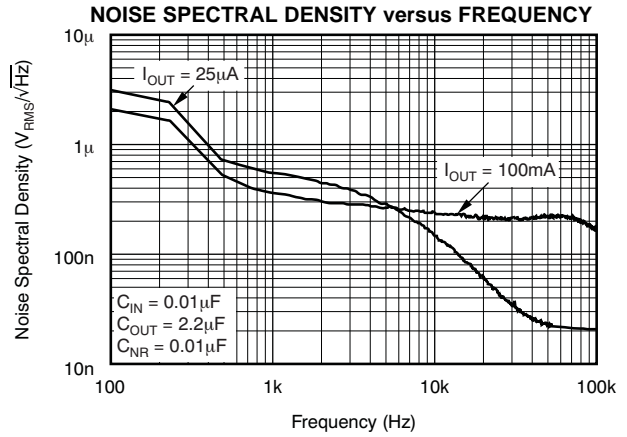


Figure 20.

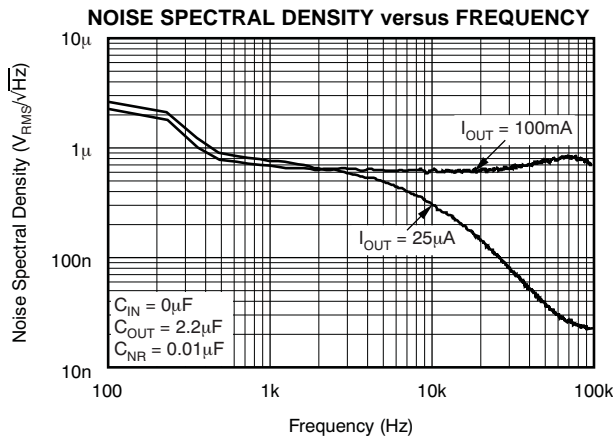


Figure 21.

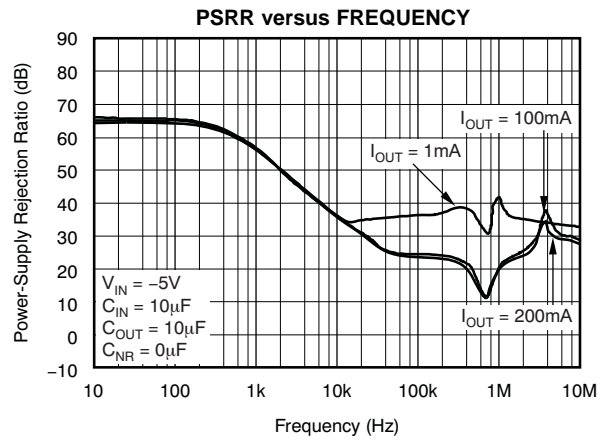


Figure 22.

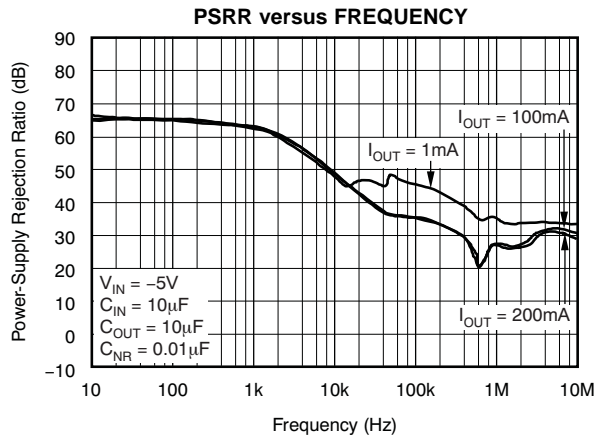


Figure 23.

APPLICATION INFORMATION

DEVICE OPERATION

The TPS723xx-Q1 is a low-dropout negative linear voltage regulator with a rated current of 200 mA. It features very low noise and high power-supply rejection ratio (PSRR), making it ideal for high-sensitivity analog and RF applications. A shutdown mode is available, reducing ground current to 2 μ A maximum over temperature and process. The TPS723xx-Q1 comes in a small SOT23 package, specified over a -40°C to 125°C junction-temperature range.

ENABLE

The enable pin is active above 1.5 V and below -1.5 V, allowing control by a standard TTL signal or by connection to V_I if not used. Driving the pin to GND turns off most internal circuitry, putting the TPS723xx-Q1 into shutdown mode, drawing 2- μ A maximum ground current.

CAPACITOR SELECTION FOR STABILITY

Use appropriate input and output capacitors for the intended application. The TPS723xx-Q1 only requires the use of a 2.2- μ F ceramic output capacitor for stable operation. Both the capacitor value and ESR affect stability, output noise, PSRR, and transient response. For typical applications, a 2.2- μ F ceramic output capacitor located close to the regulator is sufficient.

OUTPUT NOISE

Without external bypassing, output noise of the TPS723xx-Q1 from 10 Hz to 100 kHz is 200 μV_{RMS} typical. The dominant contributor to output noise is the internal band-gap reference. Adding an external 0.01- μ F capacitor to ground reduces the noise to 60 μV_{RMS} . To achieve best noise performance, use appropriate low-ESR capacitors for bypassing noise at the NR and OUT pins. See Figure 18 in the Typical Characteristics section.

POWER-SUPPLY REJECTION

The TPS723xx-Q1 offers a very high PSRR for applications with noisy input sources or highly sensitive output supply lines. For best PSRR, use high-quality input and output capacitors.

CURRENT LIMIT

The TPS723xx-Q1 has internal circuitry that monitors and limits output current to protect the regulator from damage under all load conditions. When output current reaches the output-current limit (550 mA typical), protection circuitry turns on, reducing output voltage to ensure that current does not increase. See Figure 8 in the Typical Characteristics section.

Do not drive the output more than 0.3 V above the input. Doing so biases the body diode in the pass FET, allowing current to flow from the output to the input. The device does not limit this current. If this condition is likely, take care to limit the reverse current externally.

THERMAL PROTECTION

As protection from damage due to excessive junction temperatures, the TPS723xx-Q1 has internal protection circuitry. When junction temperature reaches approximately 165°C , the output device turns off. After the device has cooled by about 20°C , the output device turns on, allowing normal operation. For reliable operation, design is for worst-case junction temperature of $\leq 125^{\circ}\text{C}$, taking into account worst-case ambient temperature and load conditions.

ADJUSTABLE VOLTAGE APPLICATIONS

The TPS72301-Q1 allows designers to specify any output voltage from -10 V to -1.2 V. As shown in the application circuit in Figure 24, use of an external resistor divider scales the output voltage (V_{OUT}) to the reference voltage. For best accuracy, use precision resistors for R1 and R2. Use the equations in Figure 24 to determine the values for the resistor divider.

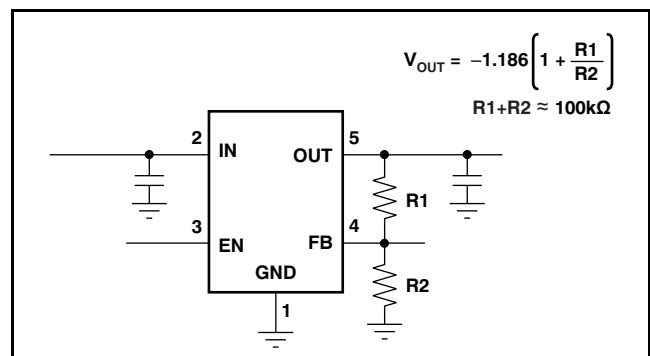


Figure 24. TPS72301-Q1 Adjustable LDO Regulator Programming

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| TPS72301QDBVRQ1 | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | PPHQ | Samples |
| TPS72325QDBVRQ1 | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 125 | PSBQ | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TPS72301-Q1, TPS72325-Q1 :

- Catalog: [TPS72301](#), [TPS72325](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TPS72301QDBVRQ1 | SOT-23 | DBV | 5 | 3000 | 179.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS72325QDBVRQ1 | SOT-23 | DBV | 5 | 3000 | 179.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |

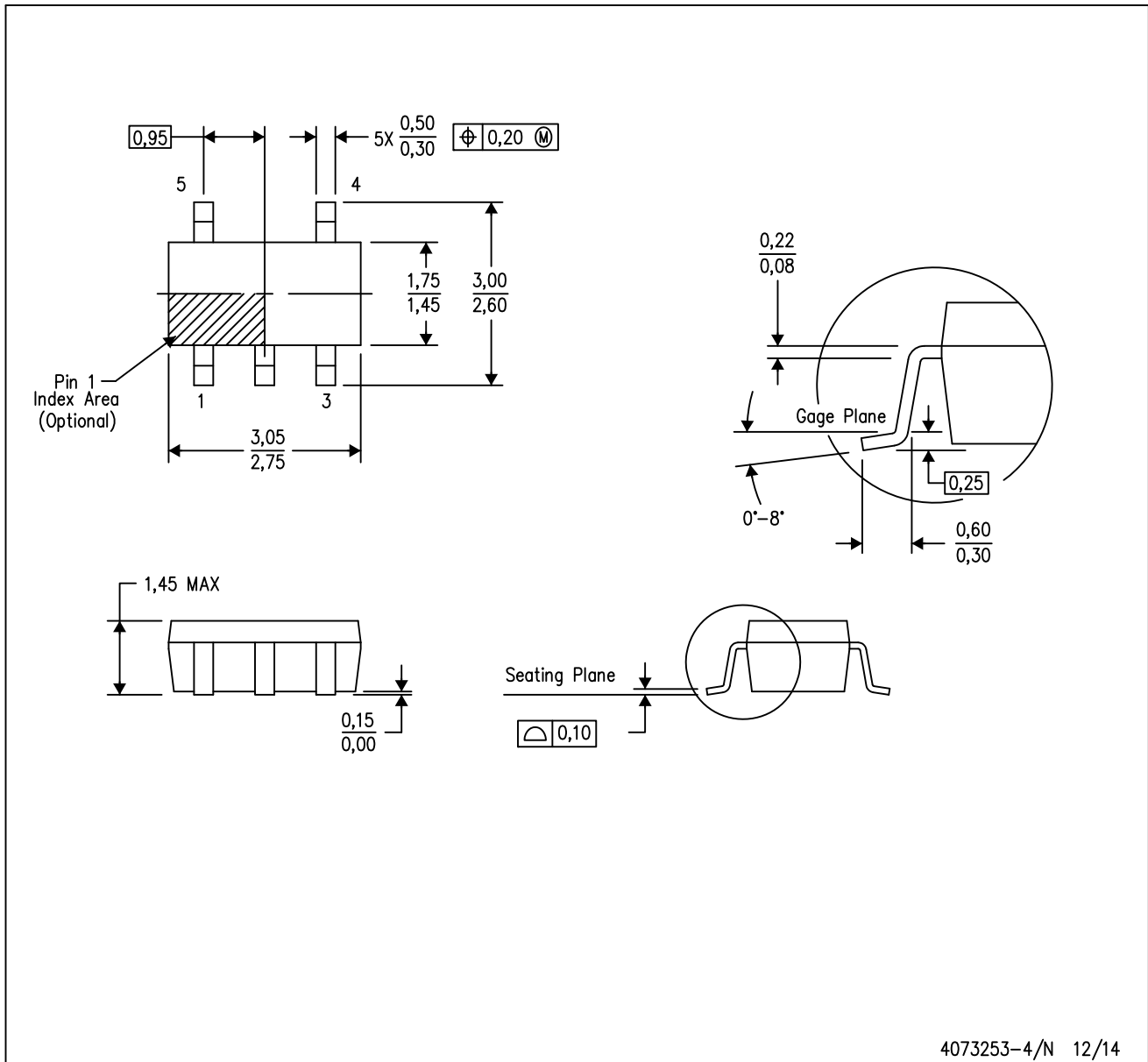
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TPS72301QDBVRQ1 | SOT-23 | DBV | 5 | 3000 | 203.0 | 203.0 | 35.0 |
| TPS72325QDBVRQ1 | SOT-23 | DBV | 5 | 3000 | 203.0 | 203.0 | 35.0 |

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.

DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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